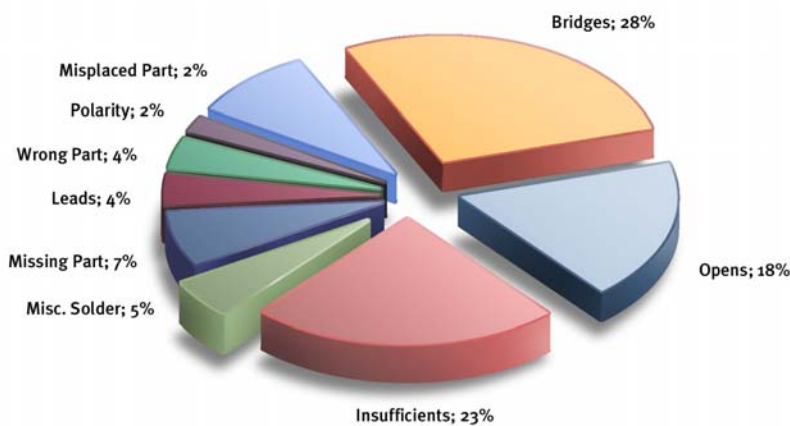


ACHIEVING HIGH YIELDS WITH SOLDER PASTE INSPECTION AT TBP ELECTRONICS

High yields and defect-free electronics manufacturing are key goals of **tpb electronics**, one of the most dynamic EMS companies in northern Europe today. Their customers are demanding, and keeping them happy has made **tpb**, founded in 1976, a market leader in state-of-the-art contract printed circuit assembly and high-tech electronics production. **tpb** is ISO 9001-2000 & 14001, AQAP 2120-2003, IEC 61508 and TL 9000 certified, so they clearly take quality issues very seriously.



tpb, with production facilities in Geel (Belgium) and Dirksland (the Netherlands), builds high-end multilayer products containing very valuable components. These products require high first-pass yields. To facilitate first pass yield improvement, **tpb** invested in the Koh Young 3D solder paste inspection equipment 3030VAL for three of their production lines in Geel. The Koh Young system, using a patented profilometry technique, delivers true in-line 100% 3D shadow-free solder paste inspection for highest precision and accuracy.

Production is in small batches, which requires a very short changeover time. The Koh Young inspection system is the best fit for **tpb's** needs, because it offers both short changeover and programming times. This means faster production with fewer interruptions and delays.

“The improvements that we have realized since implementing the Koh Young systems have exceeded our expectations” said Anton Hermus, COO of **tpb**. “Our investment has been completely justified by the results, quite simply a ROI that no other systems have matched. Our plan is to equip all of our other production lines with Koh Young solder paste inspection systems, to guarantee the yields we need and to ensure that no solder paste-related defects go on to create headaches further down the production line.”

Volumes of studies have shown, and it is a general consensus within the industry, that the majority of defects in the SMT production line originate in the solder paste printing process. Catching those defects as early as possible boosts yields and end-product quality, and prevents unnecessary rework and higher per-piece production costs. With today's tight profit margins, detecting solder paste defects and process problems upstream directly impacts the profitability of the company. Considerable costs reductions are realized with the early detection of defects, and elimination of ‘false calls’ with otherwise good solder paste prints. When combined with a rapidly programmable system and stable SPC-Plus software, the printing process can be optimized to prevent structural causes and capture accidental screen printing equipment defects, such as a squeegee blade problem.

The story of **tpb electronics** is a case in point: comprehensive solder paste inspection with the Koh Young system, offering a short change-over time and minimal programming time, can minimize Cost of Ownership and improve overall yields and profitability quickly.

UPCOMING EXHIBITIONS

REPORT SMT SHOW, NUREMBERG

At SMT Hybrid Show in Nuremberg, Germany, 3-5 June, Koh Young Technology was selected to be the measurement system in Paste Printer Benchmark line, organised by the EPP magazine. With much attention from show visitors, live printing of 4 different screen printers took place 5 times a day. Koh Young displayed measurement results after each print within 3 minutes to show highlights and possible defects. While Speedprint, DEK, EKRA and essemtec were competing for best and most consistent print results, Koh Young provided them with vital feedback for print optimisation over the 3 day event. Articles with a full presentation and discussion of the results will be published in the EPP and EPP Europe magazines.

JPCA SHOW, TOKYO BIG SIGHT, JAPAN, 11-13 JUNE 2008.

At this show Koh Young will display the latest SPI equipment. The aSPIre with SPC-Plus, the Prime with Bump inspection and the KY 8030 equipment. A separate demo area for SPC-Plus software demonstrations is inside the booth 1G/09



SEMICON WEST, MOSCONE CENTER, SAN FRANCISCO, CA, USA, 15-17 JULY 2008

This semi conductor show is focused on the manufacturing of semicon products. Koh Young will be present with our Prime, the first 3D bump inspection system.